



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Sectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-06-08
<b>Company Unique ID</b>	NL 008751171801		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Giovanni Giacobello	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ESDA25-4BP6	CJP1*DAW25V4	A	9955	2018-06-08
	Amount	UoM	Unit type	ST ECOPACK Grade
	3.64	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	210	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOT	1.7 - 1.5 - 0.525	6	gull wing	
Comment	Package: SOT 666			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			TRUE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			FALSE
Substance	amount in product (mg)	Application	ppm in product

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	CJP1*DAW25V4					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	0.235	mg	supplier	die	Silicon (Si)	7440-21-3		0.219	mg	931915	60165
				supplier	metallization	Aluminium (Al)	7429-90-5		0.010	mg	42553	2747
				supplier	Passivation	Silicon Oxide	7631-86-9		0.006	mg	25532	1648
Leadframe	M-004 Copper and its alloys	1.672	mg	supplier	alloy	Copper (Cu)	7440-50-8		1.646	mg	984450	452198
				supplier	alloy	Zinc (Zn)	7440-66-6		0.003	mg	1795	824
				supplier	alloy	Tin (Sn)	7440-31-5		0.004	mg	2392	1099
				supplier	alloy	Chromium (Cr)	7440-47-3		0.004	mg	2392	1099
				supplier	metallization	Silver (Ag)	7440-22-4		0.015	mg	8971	4121
				supplier	glue	Epoxyde Bisphenol A Resin	25068-38-6		0.004	mg	93023	1099
Die attach	0.043	mg	supplier	glue	Silica, vitreous	60676-86-0		0.003	mg	69767	824	
			supplier	glue	Ethoxyethoxy-ethyl Acetate	112-15-2		0.009	mg	209302	2473	
			supplier	glue	Aluminium oxide	1344-28-1		0.019	mg	441860	5220	
			supplier	glue	Bisphenol A diglycidyl ether polymer	25036-25-3		0.007	mg	162791	1923	
			supplier	glue	Diaminodiphenylsulfone	80-08-0		0.001	mg	23257	273	
			supplier	wire	Copper (Cu)	7440-50-8		0.020	mg	952381	5495	
Bonding wires	M-004 Copper and its alloys	0.021	mg	supplier	wire	Palladium (Pd)	7440-05-3		0.001	mg	47619	275
				supplier	mold compound	Silica, vitreous	60676-86-0		1.253	mg	785088	344231
				supplier	mold compound	epoxy resin	Proprietary		0.207	mg	129699	56868
				supplier	mold compound	phenol resin	9003-35-4		0.096	mg	60150	26374
				supplier	mold compound	metal hydroxide	Proprietary		0.032	mg	20050	8791
connections coating	Solder	0.073	mg	supplier	mold compound	Carbon black	1333-86-4		0.008	mg	5013	2198
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.073	mg	1000000	20055